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- (57)

ABSTRACT

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G03F 7/004 (2006.01)

A method of forming an organic material pattern film, the method including: forming partition walls on a first region of a first layer, the partition walls including a photosensitive compound including a resorcinarene, the resorcinarene including a perfluorocarbon group; forming a second layer including an organic material on a second region of the first layer, the second region being defined by the partition walls; removing the partition walls.

S'14

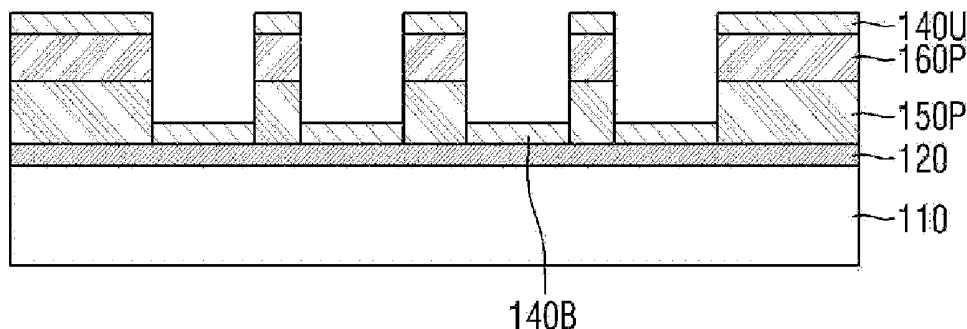


FIG.1

S1

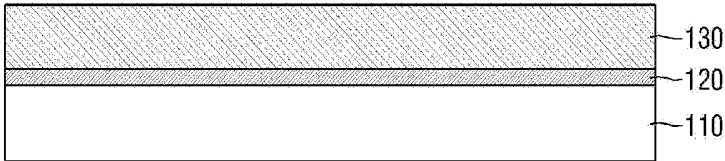


FIG.2

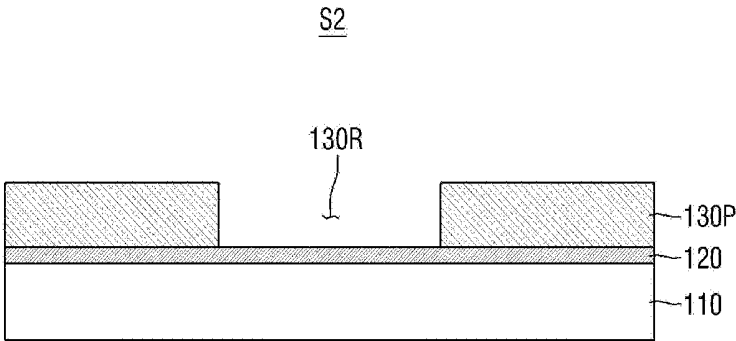


FIG.3

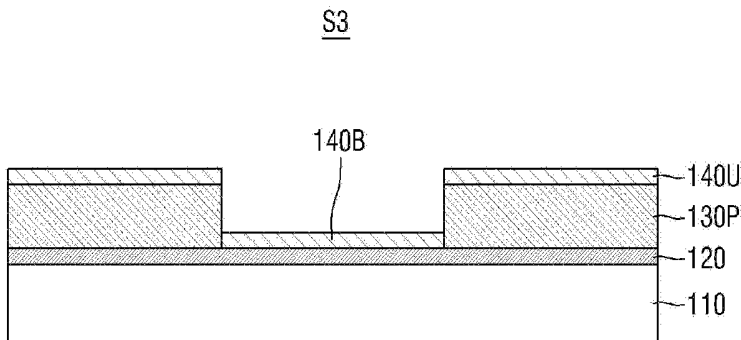


FIG.4

S4

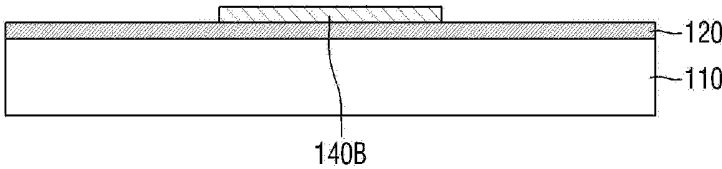


FIG.5

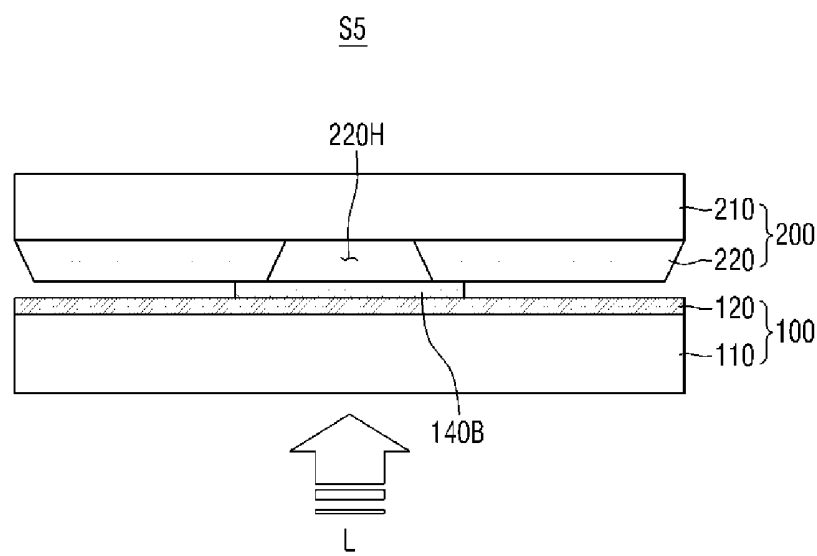


FIG.6

S6

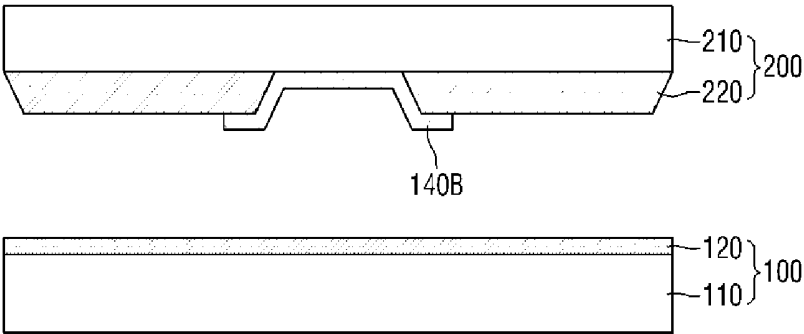


FIG.7

S11

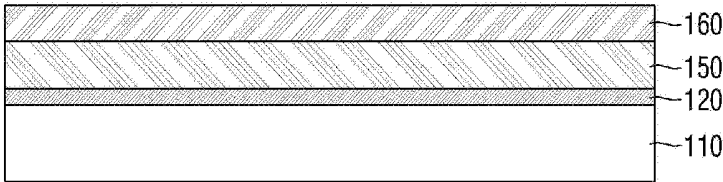


FIG.8

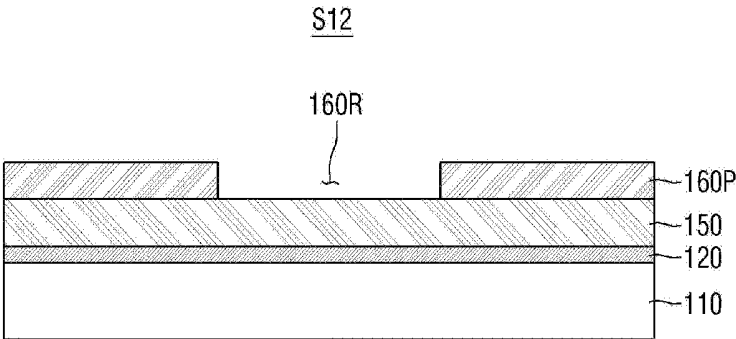


FIG.9

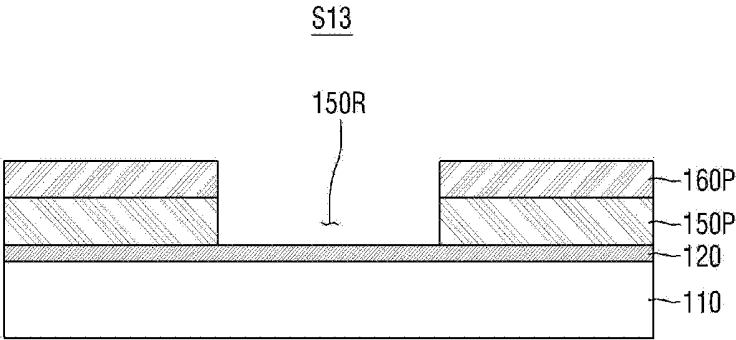


FIG.10

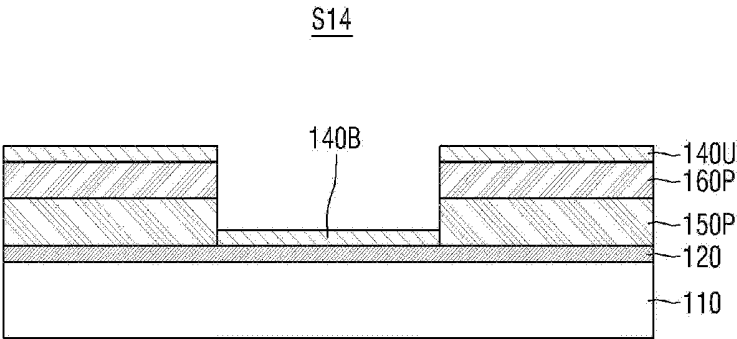


FIG.11

S15

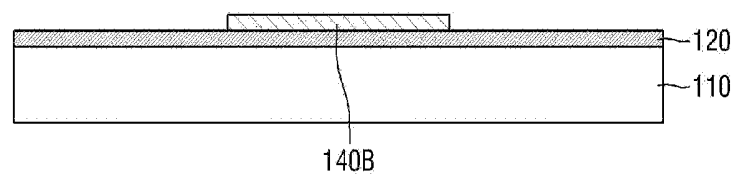


FIG.12

S'1

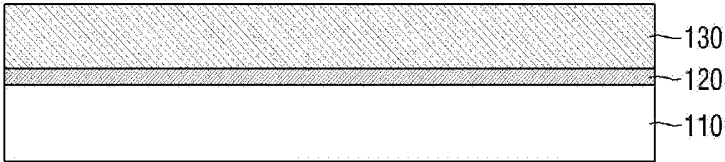


FIG.13

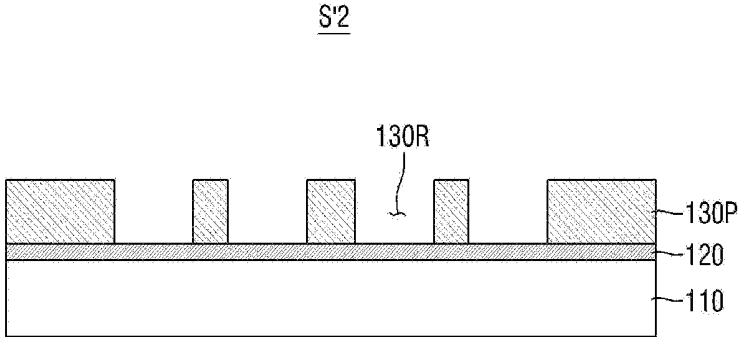


FIG.14

S'3

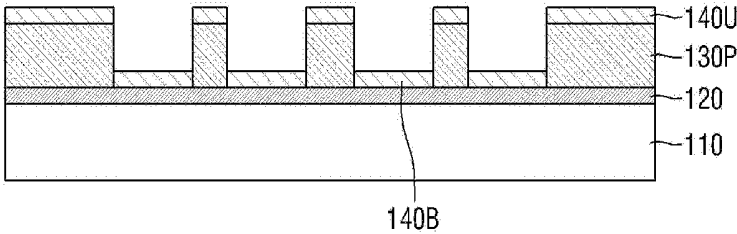


FIG.15

S4

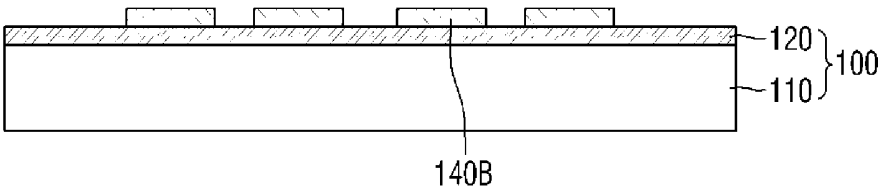


FIG.16

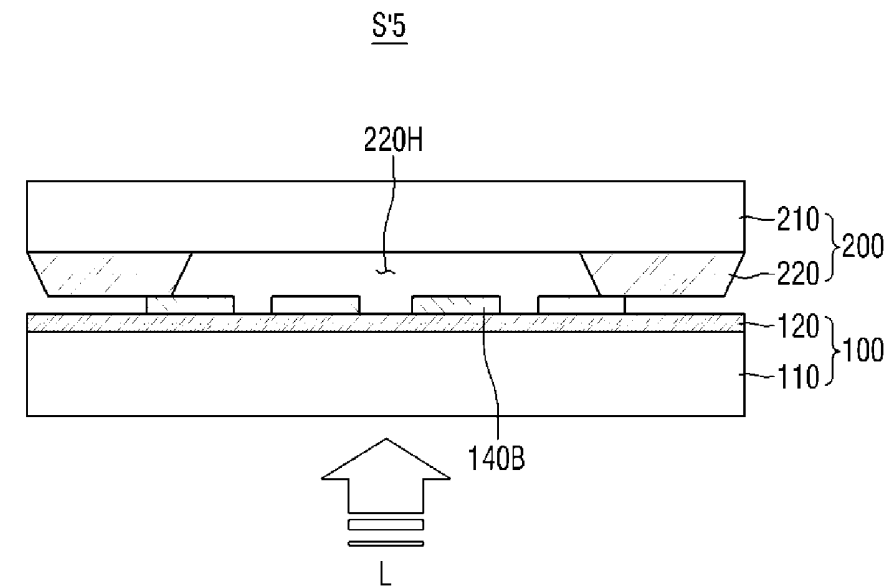


FIG.17

S'6

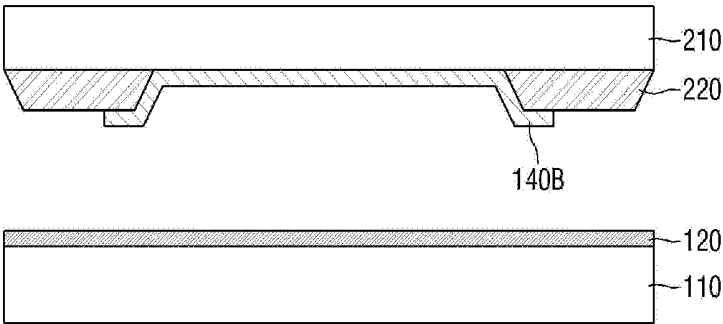


FIG.18

S'11

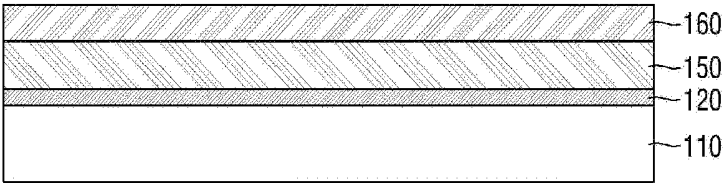


FIG.19

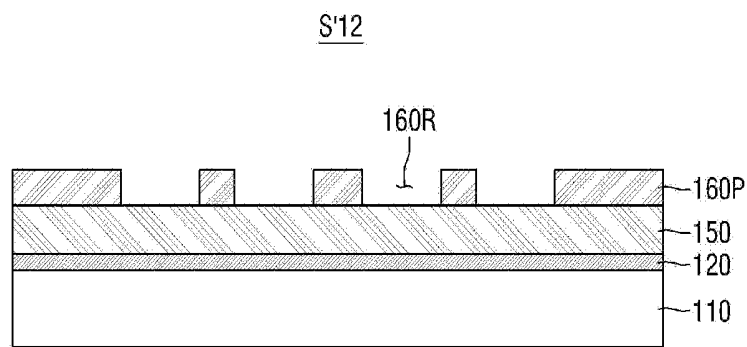


FIG.20

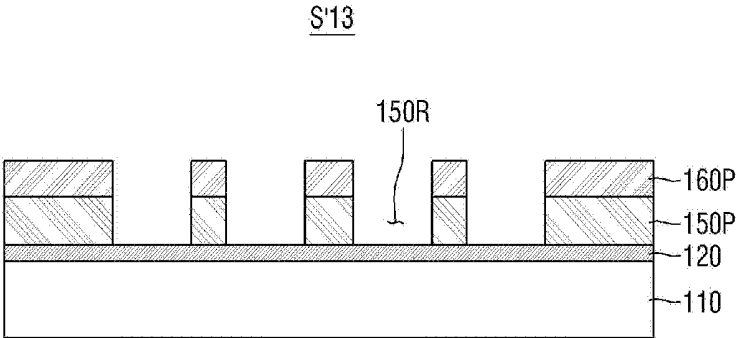


FIG.21

S'14

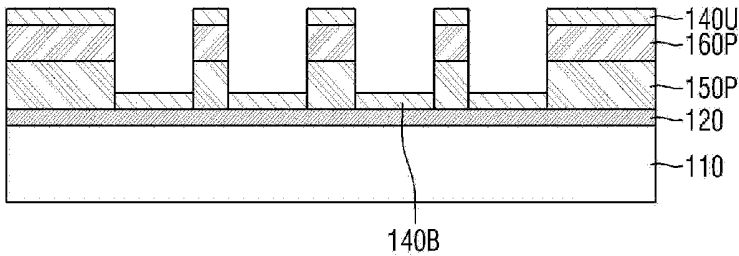
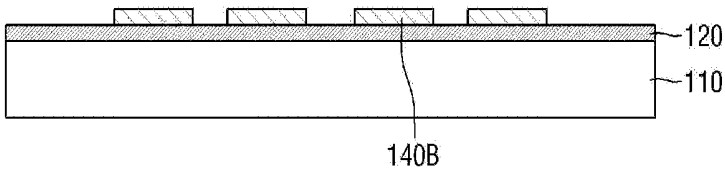


FIG.22

S'15



**METHOD OF MANUFACTURING
SUBSTRATE OF ORGANIC
LIGHT-EMITTING DISPLAY DEVICE**

**CROSS-REFERENCE TO RELATED
APPLICATIONS**

[0001] This application is a Continuation of U.S. patent application Ser. No. 15/583,650, filed on May 1, 2017, which is a Continuation of U.S. patent application Ser. No. 15/082,726, filed on Mar. 28, 2016, now issued as U.S. Pat. No. 9,673,396, which is a Divisional of U.S. patent application Ser. No. 14/668,351, filed on Mar. 25, 2015, now issued as U.S. Pat. No. 9,577,195, which claims priority from and the benefit of Korean Patent Application No. 10-2014-0141764, filed on Oct. 20, 2014, each of which is hereby incorporated by reference for all purposes as if fully set forth herein.

BACKGROUND

Field

[0002] Exemplary embodiments relate to a method of manufacturing a substrate of an organic light-emitting display device.

Discussion of the Background

[0003] An organic light-emitting display device includes an anode electrode, a cathode electrode, and organic layers disposed between the anode electrode and the cathode electrode. The organic layers may include a hole injection layer (HIL), a hole transport layer (HTL), an electron transport layer (ETL), an electron injection layer (EIL), and an emission layer (EML). The organic electroluminescence (EL) device may be classified as a high molecular organic EL device or a low molecular organic EL device according to the type of material that form the organic layers, and particularly, the EML.

[0004] In case of a low-molecular organic light-emitting display device, the organic layers may be patterned via a method using a fine metal mask (FMM). In case of a high-molecular organic light-emitting display device, the organic layers may be patterned via an inkjet printing method or a laser induced thermal imaging (LITI) method. The patterning of a high molecular organic layer via the LITI method may require a light source, a target substrate on which an organic EL device is to be formed, and a donor film. The donor film typically includes a base substrate and a transfer layer including, for instance, a photothermal conversion layer and an organic film. The organic film may be formed on an entire surface of the photothermal conversion layer. According to the LITI method, the organic film can be transferred onto the target substrate by selectively applying laser light to a particular region on the donor film to enable the photothermal conversion layer to generate heat in the particular region.

[0005] The above information disclosed in this Background section is only for enhancement of understanding of the background of the inventive concept, and, therefore, it may contain information that does not form the prior art that is already known in this country to a person of ordinary skill in the art.

SUMMARY

[0006] Exemplary embodiments provide a method of manufacturing a substrate of an organic light-emitting display device with improved processability.

[0007] Additional aspects will be set forth in the detailed description which follows, and, in part, will be apparent from the disclosure, or may be learned by practice of the inventive concept.

[0008] According to one or more exemplary embodiments, a method of manufacturing a substrate of an organic light-emitting display device, the method including: forming, on a first surface of a transparent substrate, a photothermal conversion layer configured to convert incident light into thermal energy; forming partition walls on the first surface in a first region of the photothermal conversion layer, the partition walls including a photosensitive compound including a resorcinarene, the resorcinarene including a perfluorocarbon group; forming an organic material layer on the first surface in a second region of the photothermal conversion layer, the second region being defined by the partition walls; removing the partition walls; placing a target substrate over the organic material layer; and applying light to a second surface of the transparent substrate, the second surface being opposite the first surface of the transparent substrate.

[0009] According to one or more exemplary embodiments, a method of manufacturing a substrate of an organic light-emitting display device, the method including: forming, on a first surface of a transparent substrate, a photothermal conversion layer configured to convert incident light into thermal energy; forming a fluorine-based resin layer on the photothermal conversion layer, the fluorine-based resin layer including a fluorine-based resin; forming first partition walls on the first surface in a first region of the photothermal conversion layer, the first partition walls including a photosensitive polymer compound; forming second partition walls using the first partition walls as a mask, the second partition walls including the fluorine-based resin; forming an organic material layer on the first surface of a second region of the photothermal conversion layer, the second region being defined by the first partition walls and the second partition walls; removing the first partition walls and the second partition walls; placing a target substrate over the organic material layer; and applying light to a second surface of the transparent substrate, the second surface being opposite the first surface of the transparent substrate.

[0010] The foregoing general description and the following detailed description are exemplary and explanatory and are intended to provide further explanation of the claimed subject matter.

BRIEF DESCRIPTION OF THE DRAWINGS

[0011] The accompanying drawings, which are included to provide a further understanding of the invention and are incorporated in and constitute a part of this specification, illustrate embodiments of the inventive concept, and together with the description serve to explain the principles of the inventive concept.

[0012] FIGS. 1, 2, 3, and 4 are cross-sectional views illustrating processes of manufacturing a transfer substrate, according to one or more exemplary embodiments.

[0013] FIGS. 5 and 6 are cross-sectional views of a substrate of an organic light-emitting display device at various stages of manufacture, according to one or more exemplary embodiments.

[0014] FIGS. 7, 8, 9, 10, and 11 are cross-sectional views of a transfer substrate at various stages of manufacture, according to one or more exemplary embodiments.

[0015] FIGS. 12, 13, 14, and 15 are cross-sectional views of a transfer substrate at various stages of manufacture, according to one or more exemplary embodiments.

[0016] FIGS. 16 and 17 are cross-sectional views of a substrate of an organic light-emitting display device at various stages of manufacture, according to one or more exemplary embodiments.

[0017] FIGS. 18, 19, 20, 21, and 22 are cross-sectional views of a transfer substrate at various stages of manufacture, according to one or more exemplary embodiments.

DETAILED DESCRIPTION OF THE ILLUSTRATED EMBODIMENTS

[0018] In the following description, for the purposes of explanation, numerous specific details are set forth in order to provide a thorough understanding of various exemplary embodiments. It is apparent, however, that various exemplary embodiments may be practiced without these specific details or with one or more equivalent arrangements. In other instances, well-known structures and devices are shown in block diagram form in order to avoid unnecessarily obscuring various exemplary embodiments.

[0019] In the accompanying figures, the size and relative sizes of layers, films, panels, regions, etc., may be exaggerated for clarity and descriptive purposes. Also, like reference numerals denote like elements.

[0020] When an element or layer is referred to as being “on,” “connected to,” or “coupled to” another element or layer, it may be directly on, connected to, or coupled to the other element or layer or intervening elements or layers may be present. When, however, an element or layer is referred to as being “directly on,” “directly connected to,” or “directly coupled to” another element or layer, there are no intervening elements or layers present. For the purposes of this disclosure, “at least one of X, Y, and Z” and “at least one selected from the group consisting of X, Y, and Z” may be construed as X only, Y only, Z only, or any combination of two or more of X, Y, and Z, such as, for instance, XYZ, XYY, YZ, and ZZ. Like numbers refer to like elements throughout. As used herein, the term “and/or” includes any and all combinations of one or more of the associated listed items.

[0021] Although the terms first, second, etc. may be used herein to describe various elements, components, regions, layers, and/or sections, these elements, components, regions, layers, and/or sections should not be limited by these terms. These terms are used to distinguish one element, component, region, layer, and/or section from another element, component, region, layer, and/or section. Thus, a first element, component, region, layer, and/or section discussed below could be termed a second element, component, region, layer, and/or section without departing from the teachings of the present disclosure.

[0022] Spatially relative terms, such as “beneath,” “below,” “lower,” “above,” “upper,” and the like, may be used herein for descriptive purposes, and, thereby, to describe one element or feature’s relationship to another element(s) or feature(s) as illustrated in the drawings. Spatially relative terms are intended to encompass different orientations of an apparatus in use, operation, and/or manufacture in addition to the orientation depicted in the drawings. For example, if the apparatus in the drawings is turned over, elements described as “below” or “beneath” other elements or features would then be oriented “above” the other elements or features. Thus, the exemplary term “below” can encompass both an orientation of above and below. Furthermore, the apparatus may be otherwise oriented (e.g., rotated 90 degrees or at other orientations), and, as such, the spatially relative descriptors used herein interpreted accordingly.

[0023] The terminology used herein is for the purpose of describing particular embodiments and is not intended to be limiting. As used herein, the singular forms, “a,” “an,” and “the” are intended to include the plural forms as well, unless the context clearly indicates otherwise. Moreover, the terms “comprises,” “comprising,” “includes,” and/or “including,” when used in this specification, specify the presence of stated features, integers, steps, operations, elements, components, and/or groups thereof, but do not preclude the presence or addition of one or more other features, integers, steps, operations, elements, components, and/or groups thereof.

[0024] Various exemplary embodiments are described herein with reference to sectional illustrations that are schematic illustrations of idealized exemplary embodiments and/or intermediate structures. As such, variations from the shapes of the illustrations as a result, for example, of manufacturing techniques and/or tolerances, are to be expected. Thus, exemplary embodiments disclosed herein should not be construed as limited to the particular illustrated shapes of regions, but are to include deviations in shapes that result from, for instance, manufacturing. For example, an implanted region illustrated as a rectangle will, typically, have rounded or curved features and/or a gradient of implant concentration at its edges rather than a binary change from implanted to non-implanted region. Likewise, a buried region formed by implantation may result in some implantation in the region between the buried region and the surface through which the implantation takes place. Thus, the regions illustrated in the drawings are schematic in nature and their shapes are not intended to illustrate the actual shape of a region of a device and are not intended to be limiting.

[0025] Unless otherwise defined, all terms (including technical and scientific terms) used herein have the same meaning as commonly understood by one of ordinary skill in the art to which this disclosure is a part. Terms, such as those defined in commonly used dictionaries, should be interpreted as having a meaning that is consistent with their

meaning in the context of the relevant art and will not be interpreted in an idealized or overly formal sense, unless expressly so defined herein.

[0026] FIGS. 1, 2, 3, and 4 are cross-sectional views illustrating processes S1, S2, S3, and S4, respectively, of manufacturing a transfer substrate, according to one or more exemplary embodiments.

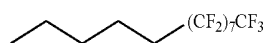
[0027] Referring to FIG. 1, a photothermal conversion layer 120 is formed on an entire first surface of a transparent substrate 110, and a photosensitive compound layer 130, which includes a resorcinarene containing a perfluorocarbon group, is formed on an entire first surface of the photothermal conversion layer 120.

[0028] The transparent substrate 110 may be transparent (or at least translucent) to transmit light emitted from a light source (not illustrated) therethrough. For example, the transparent substrate may be at least one of, but is not limited to, a glass substrate, a quartz substrate, and a synthetic resin substrate formed of a transparent polymer material with high optical transmissivity, such as polyester, polyacryl, polyepoxy, polyethylene, polystyrene, and/or polyethylene terephthalate.

[0029] The light source may be at least one of a flash lamp, a tungsten halogen lamp and a laser beam. The light source is disposed below a second surface of the transparent substrate 110, as illustrated in FIG. 5 as light source L. A laser beam may be applied to scan the entire second surface of the transparent substrate 110, or may be selectively applied to an organic material layer formed in a particular region.

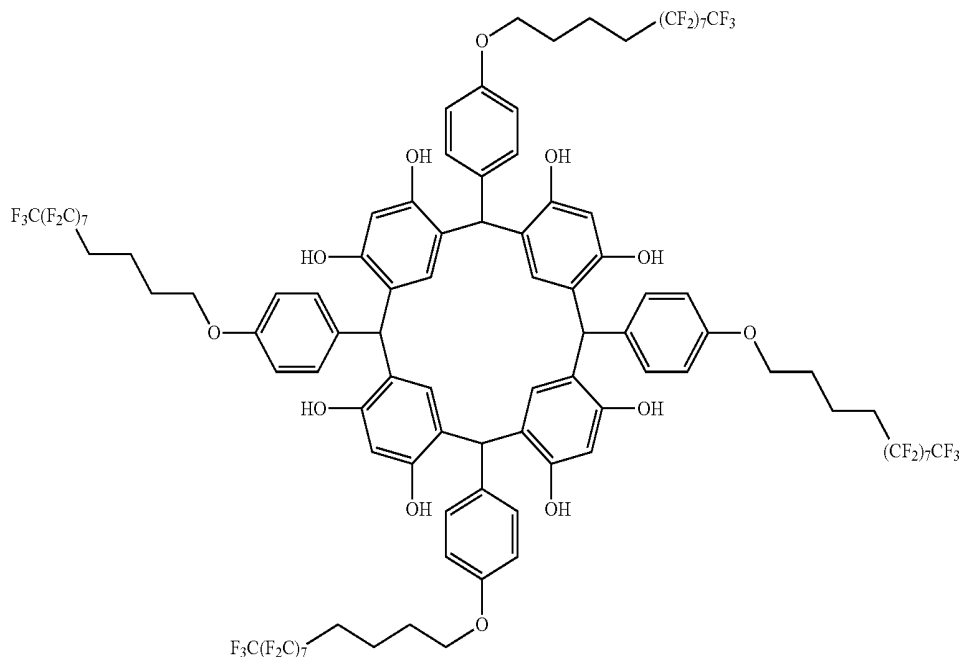
[0030] The photothermal conversion layer 120 is formed on the entire first surface of the transparent substrate 110. The photothermal conversion layer 120 may absorb light within an infrared-visible light range of the light transmitted thereto through the transparent substrate 110, and may convert the absorbed light into thermal energy. For example, the photothermal conversion layer 120 may be formed of at least one of a metal material with relatively high light absorptivity, such as molybdenum (Mo), chromium (Cr), titanium (Ti), tin (Sn), tungsten (W), and an alloy thereof, or any other suitable material.

[0031] The photothermal conversion layer 120 may be formed by various methods, for example, but not limited to, sputtering, electron beam deposition and vacuum deposition. The photosensitive compound layer 130, which includes a resorcinarene containing a perfluorocarbon group, may be formed on the entire first surface of the photothermal conversion layer 120. The resorcinarene containing a perfluorocarbon group may be material immiscible with an organic material. For example, the resorcinarene containing a perfluorocarbon group may include, but is not limited to, a resorcinarene of Formula (1) and a resorcinarene of Formula (2), wherein R¹ is



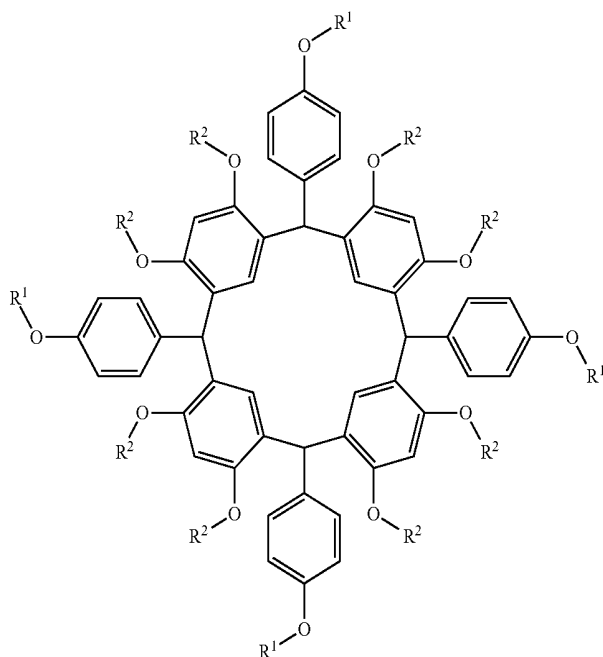
and R² is a tert-butoxycarbonyl (t-butoxycarbonyl) group:

Formula (1)



-continued

Formula (2)



[0032] The photosensitive compound layer **130**, which includes the resorcinarene containing a perfluorocarbon group, may include at least one of the resorcinarene of Formula (1), the resorcinarene of Formula (2), and a mixture thereof.

[0033] The photosensitive compound layer **130**, which includes the resorcinarene containing a perfluorocarbon group, may also include a photo-acid generator. For example, the photo-acid generator may be, but is not limited to, N-nonafluorobutane-sulfonyloxy-1,8-naphthalimide, N-nonafluoropropane-sulfonyloxy-1,8-naphthalimide, N-nonafluoroethane-sulfonyloxy-1,8-naphthalimide, N-nonafluoromethane-sulfonyloxy-1,8-naphthalimide, triphenylsulfonium perfluorooctanesulfonate, triphenylsulfonium perfluorobutanesulfonate, triphenylsulfonium trifluoromethanesulfonate, triphenylsulfonium hexafluorophosphate, triphenylsulfonium hexafluoroantimonate, diphenyliodonium perfluorooctanesulfonate, diphenyliodonium perfluorobutanesulfonate, diphenyliodonium trifluoromethanesulfonate, diphenyliodonium hexafluorophosphate, diphenyliodonium hexafluoroantimonate, n-hydroxynaphthalimide perfluorobutanesulfonate, n-hydroxynaphthalimide trifluoromethanesulfonate and/or a mixture thereof.

[0034] FIG. 2 illustrates a process of performing photolithography on the photosensitive compound layer **130**, which includes the resorcinarene containing a perfluorocarbon group.

[0035] The process of performing photolithography on the photosensitive compound layer **130**, which includes the resorcinarene containing a perfluorocarbon group, removes part of the photosensitive compound layer **130** overlapping a second region of the photothermal conversion layer **120** while leaving the remaining part of the photosensitive compound layer **130** overlapping a first region of the photothermal conversion layer **120**. The first region is a region where an organic material layer **140B**, which will be

described in FIG. 3, is not formed, and the second region is a region where the organic material layer **140B** is formed. The second region corresponds to a pixel region of a target substrate to be transferred (i.e., the substrate of an organic light-emitting display device), which is defined by a pixel-defining layer.

[0036] Portions of the photosensitive compound layer **130** remaining in the first region of the photothermal conversion layer **120** may serve as partition walls for defining the second region of the photothermal conversion layer **120**. The portions of the photosensitive compound layer **130** remaining in the first region of the photothermal conversion layer **120** will hereinafter be referred to as first partition wall patterns **130P**, and a region between the first partition wall patterns **130P** will hereinafter be referred to as a first incision pattern **130R**. The second region of the photothermal conversion layer **120** is exposed through the first incision pattern **130R**.

[0037] The first partition wall patterns **130P** may be formed by placing a mask (not illustrated) over the photosensitive compound layer **130** to protect the part of the photosensitive compound layer **130** overlapping the first region of the photothermal conversion layer **120**, and selectively exposing it to light and developing the part of the photosensitive compound layer **130** overlapping the second region of the photothermal conversion layer **120** to remove the photosensitive compound layer **130** from the second region of the photothermal conversion layer **120**. The first incision pattern **130R** is formed where the photosensitive compound layer **130** is removed, and corresponds to the second region of the photothermal conversion layer **120**.

[0038] FIG. 3 illustrates a process of forming an organic material layer **140U** on the first partition wall patterns **130P** and the organic material layer **140B** on the surface of the second region of the photothermal conversion layer **120**, which is exposed through the first incision pattern **130R**.

[0039] The organic material layers **140U** and **140B** may include organic materials for forming organic layers of an organic light-emitting display device. More specifically, the organic material layers **140U** and **140B** may include an organic material for forming an emission layer (EML), an organic material for forming a hole injection layer (HIL), an organic material for forming a hole transport layer (HTL), an organic material for forming an electron injection layer (EIL), and an organic material for forming an electron transport layer (ETL).

[0040] The first partition wall patterns **130P** may include a fluorine-based material that is immiscible with an organic material, and, as such, the first partition wall patterns **130P** may not deteriorate the physical properties of the organic material layers **140U** and **140B**.

[0041] Conventionally, however, a photosensitive resin composition often causes a reaction with an organic material, and, thus, may cause the deterioration of the physical properties of an organic material layer. As a result, it is not easy to directly pattern an organic material layer when using a photosensitive resin composition. On the other hand, in the method of manufacturing a transfer substrate according to the exemplary embodiments, an organic material layer may be directly patterned using a fluorine-based material that is immiscible with an organic material without deteriorating the physical properties of the organic material layer.

[0042] FIG. 4 illustrates a process of removing the first partition wall patterns **130P** by using a lift-off method.

[0043] The first partition wall patterns **130P** may be lifted off using a fluorine-based solvent. The fluorine-based solvent may be, but is not limited to, hydrofluoroether (HFE). Since the fluorine-based solvent does not affect the organic material layer **140B**, the fluorine-based solvent, unlike a typical organic solvent, does not deteriorate the physical properties of the organic material layer **140B**. Examples of the HFE may include, but are not limited to, methyl nonafluorobutyl ether, methyl nonafluoroisobutyl ether, an isomeric mixture of methyl nonafluorobutyl ether and methyl nonafluoroisobutyl ether, ethyl nonafluorobutyl ether, ethyl nonafluoroisobutyl ether, an isomeric mixture of ethyl nonafluorobutyl ether and ethyl nonafluoroisobutyl ether, 3-ethoxy-1,1,1,2,3,4,4,5,5,6,6,6-dodecafluoro-2-trifluoromethyl-hexane, 1,1,1,2,2,3,4,4,5,5,5-decafluoro-3-methoxy-4-trifluoromethyl-pentane, and/or a mixture thereof.

[0044] Since the first partition wall patterns **130P** may be removed using the fluorine-based solvent, the organic material layer **140B** may be formed only in the second region of the photothermal conversion layer **120**.

[0045] According to one or more exemplary embodiments, a transfer substrate **100** can be formed to have a simple structure in which the transparent substrate **110** and the photothermal conversion layer **120** are stacked. As such, the structure may be free of reflective layer patterns, and, as a result, the time, effort, and cost of manufacturing a transfer substrate may be reduced.

[0046] FIGS. 5 and 6 are cross-sectional views of a substrate of an organic light-emitting display at various stages of manufacture, according to one or more exemplary embodiments.

[0047] FIG. 5 illustrates a process of applying light L to the transfer substrate **100** of FIG. 4 from below the transfer substrate **100** after placing the transfer substrate the transfer substrate **100** to face the target substrate **200**.

[0048] Referring to FIG. 5, the target substrate **200** may include a transparent substrate **210** and a pixel-defining layer **220**, which is formed on a bottom surface of the transparent substrate **210**. The target substrate **200** is a target substrate to which the organic material layer **140B** on the transfer substrate **100** is to be transferred. A region between parts of the pixel-defining layer **220** is a pixel region **220H**.

[0049] More specifically, the transfer substrate **100** is aligned with the target substrate **200** such that the second region of the photothermal conversion layer **120** can correspond to the pixel region **220H** of the target substrate **200**. Thereafter, the light L is applied to the transfer substrate **100** from below the transfer substrate **100**.

[0050] The light L, which is applied to the transfer substrate **100** from below the transfer substrate **100**, is incident upon the photothermal conversion layer **120** through the transparent substrate **110**, and the photothermal conversion layer **120** converts the light incident thereupon into heat. The heat generated by the photothermal conversion layer **120** is transmitted to the organic material layer **140B**.

[0051] FIG. 6 illustrates a process of transferring the organic material layer **140B** onto the pixel region **220H** of the target substrate **200**.

[0052] Referring to FIG. 6, the organic material layer **140B** is evaporated by the heat generated by the photothermal conversion layer **120** and is thus transferred onto a target substrate to be transferred, i.e., the target substrate **200**. The organic material layer **140B** is transferred to completely cover the pixel region **220H** of the target substrate **200**. The organic material layer **140B** may also be transferred onto the pixel-defining layer **220**.

[0053] The transfer substrate **100** from which the organic material layer **140B** is transferred onto the target substrate **200** has a structure in which the photothermal conversion layer **120** is formed on one surface of the transparent substrate **110**, and can be reused regardless of the type of organic material used or the size of a pixel region of a substrate of an organic light-emitting display device.

[0054] FIGS. 7, 8, 9, 10, and 11 are cross-sectional views of a transfer substrate at various stages of manufacture, according to one of more exemplary embodiments.

[0055] The process S11 of FIG. 7 is identical to the process S1 of FIG. 1 in that a photothermal conversion layer **120** is formed on an entire first surface of a transparent substrate **110**. However, the process S11 of FIG. 7 differs from the process S1 of FIG. 1 in that a fluorine-based resin layer **150** is formed on an entire first surface of the photothermal conversion layer **120** and a photosensitive resin composition layer **160** is formed on an entire first surface of the fluorine-based resin layer **150**.

[0056] The fluorine-based resin layer **150** is formed of a fluorine-based resin. For example, the fluorine-based resin may be, but not limited to, polytetrafluoroethylene (PTFE), poly(perfluoroalkyl acrylate) (PFA), polychlorotrifluoroethylene (PCTFE), fluorinated ethylenepropylene resin (FEP), polychloro-trifluoroethylene (PCFE), polyvinylidene fluoride (PVDF), and/or a copolymer thereof.

[0057] The photosensitive resin composition layer **160** may be formed of a photosensitive resin composition. For example, the photosensitive resin composition may encompass any kind of photosensitive resin compositions that may be commonly use in photolithography.

[0058] FIG. 8 illustrates a process of performing photolithography on the photosensitive resin composition layer

160. Referring to FIG. 8, photosensitive resin composition layer patterns may be formed by placing a mask (not illustrated) over the photosensitive resin composition layer **160** to protect part of the photosensitive resin composition layer **160** overlapping a first region of the photothermal conversion layer **120**, and selectively exposing to light and developing the remaining part of the photosensitive resin composition layer **160** overlapping a second region of the photothermal conversion layer **120**.

[0059] The photosensitive resin composition layer patterns may include second partition wall patterns **160P** and a second incision pattern **160R**, and the second incision pattern **160R** may be disposed between the second partition wall patterns **160P**.

[0060] The process **S12** of FIG. 8 differs from the process **S2** of FIG. 2 in that photosensitive resin composition layer patterns, instead of photosensitive compound layer patterns containing a resorcinarene containing a perfluorocarbon group, are formed by photolithography.

[0061] FIG. 9 illustrates a process of performing photolithography on the fluorine-based resin layer **150**. Referring to FIG. 9, the fluorine-based resin layer **150** may be patterned by using the second partition wall patterns **160P** as a mask, thereby obtaining fluorine-based resin layer patterns. The fluorine-based resin layer patterns may include third partition wall patterns **150P** and a third incision pattern **150R**, and the third incision pattern **150R** may be disposed between the third partition wall patterns **150P**.

[0062] The process **S13** of FIG. 9 differs from the process **S2** of FIG. 2 in that the surface of the second region of the photothermal conversion layer **120** is exposed through both the second incision pattern **160R** and the third incision pattern **150R**, instead of through the first incision pattern **130R** only.

[0063] The process **S14** of FIG. 10 is identical to the process **S3** of FIG. 3 in that the organic material layer **140B** is formed on the entire first surface of the photothermal conversion layer **120**. However, the process **S14** of FIG. 10 differs from the process **S3** of FIG. 3 in that an organic material layer **140U** is formed on the second partition wall patterns **160P**.

[0064] The process **S15** of FIG. 11 differs from the process **S4** of FIG. 4 in that the transfer substrate **100** is formed by lifting off both the second partition wall patterns **160P** and the third partition wall patterns **150P**, instead of lifting off only the first partition wall patterns **130P**, with the use of a fluorine-based solvent.

[0065] FIGS. 12, 13, 14, and 15 are cross-sectional views of a transfer substrate at various stages of manufacture, according to one or more exemplary embodiments.

[0066] The process **S'1** of FIG. 12 is identical to the process **S1** of FIG. 1 in that a photothermal conversion layer **120** is formed on an entire first surface of a transparent substrate **110** and a photosensitive compound layer **130**, which includes a resorcinarene containing a perfluorocarbon group, is formed on an entire first surface of the photothermal conversion layer **120**.

[0067] The processes **S'2** and **S'3** of FIGS. 13 and 14 differ from the process **S2** of FIG. 2 in that first partition wall patterns **130P** are formed overlapping the surface of a third region of the photothermal conversion layer **120**, which is provided inside a second region of the photothermal conversion layer **120**, whereas in the process **S2** of FIG. 2, only

the incision pattern **130R** is formed in the second region of the photothermal conversion layer **120**.

[0068] First incision patterns **130R**, which are isolated from each other, are arranged between the first partition wall patterns **130P** formed in the second region of the photothermal conversion layer **120**, and an organic material layer **140B** is formed on parts of the photothermal conversion layer **120** exposed between the first incision patterns **130R**.

[0069] The process **S'4** of FIG. 15 is identical to the process **S4** of FIG. 4 in that the first partition wall patterns **130P** are lifted off by using a fluorine-based solvent. However, the process **S'4** of FIG. 15 differs from the process **S4** of FIG. 4 in that a plurality of organic material layers **140B** are formed in the second region of the photothermal conversion layer isolated from one another, whereas in the process **S4** of FIG. 4, a single continuous organic material layer **140B** is formed.

[0070] FIGS. 16 and 17 are cross-sectional views of a substrate of an organic light-emitting display device at various stages of manufacture, according to one or more exemplary embodiments.

[0071] The process **S'S** of FIG. 16 is identical to the process **S5** of FIG. 5 in that the transfer substrate **100** is aligned with a target substrate to be transferred, i.e., a target substrate **200** of an organic light-emitting display device, such that the second region of the photothermal conversion layer **120** can correspond to a pixel region **220H** of the target substrate **200** and light **L** is applied to the transfer substrate **100** from below the transfer substrate **100**.

[0072] Referring to FIG. 16, the organic material layers **140B** are formed in the second region of the photothermal conversion layer **120** isolated from one another. Since the organic material layers **140B** are isolated from another, the amount by which the organic material layers **140B** is evaporated onto a target substrate may be adjusted. Accordingly, the pattern profile of an organic layer formed on the target substrate may have a surface with improved flatness.

[0073] FIG. 17 illustrates a process of evaporating the organic material layers **140B** with the use of heat generated by the photothermal conversion layer **120** to deposit an organic material layer **140B** in the pixel region **220H** of the target substrate **200**.

[0074] Referring to FIG. 17, the organic material layer **140B** may cover the entire pixel region **220H** of the target substrate **200**. The organic material layers **140B** of FIG. 16, which are isolated from one another, are evaporated and diffused into a single organic material layer **140B** that covers the entire pixel region **220H**, as illustrated in FIG. 17. The target substrate **200** of FIG. 17 differs from the target substrate **200** of FIG. 6 in that the organic material layer **140B** may have a pattern profile with improved flatness, as mentioned above.

[0075] FIGS. 18, 19, 20, 21, and 22 are cross-sectional views of a transfer substrate at various stages of manufacture, according to one or more exemplary embodiments.

[0076] The processes **S'11**, **S'12**, **S'13**, **S'14**, and **S'15** of FIGS. 18, 19, 20, 21, and 22 differ from the processes **S'1**, **S'2**, **S'3**, **S'4**, and **S'5** of FIGS. 12, 13, 14, and 15 in that a plurality of second partition wall patterns **160P** and a plurality of third partition wall patterns **150P** are formed in a second region of a photothermal conversion layer **120**, and a plurality of organic material layers **140B** are formed to be isolated from one another.

[0077] Although certain exemplary embodiments and implementations have been described herein, other embodiments and modifications will be apparent from this description. Accordingly, the inventive concept is not limited to such embodiments, but rather to the broader scope of the presented claims and various obvious modifications and equivalent arrangements.

1. A method of forming an organic material pattern film, the method comprising:

forming partition walls on a first region of a first layer, the partition walls comprising a photosensitive compound comprising a fluorine-based material;

forming a second layer including an organic material on a second region of the first layer, the second region being defined by the partition walls; and

removing the partition walls.

2. The method of claim 1, wherein the first layer includes a photo-absorbing material.

3. The method of claim 2, further comprising:

forming the first layer on a substrate before the step of forming partition walls.

4. The method of claim 2, further comprising:

forming partition walls on a third region of the first layer, the partition walls on the third region comprising the photosensitive compound,

wherein the third region is inside the second region.

5. The method of claim 2, wherein the forming of the partition walls comprises:

forming, on a first surface of the first layer, a photosensitive compound layer comprising the photosensitive compound;

placing a mask over the photosensitive compound layer and selectively exposing part of the photosensitive compound layer in the second region to light while protecting the photosensitive compound layer in the first region with the mask; and

developing and removing the photosensitive compound layer in the second region.

6. (canceled)

7. The method of claim 2, wherein the photosensitive compound further comprises a photo-acid generator.

8. The method of claim 7, wherein the photo-acid generator comprises at least one selected from the group consisting of N-nonafluorobutane-sulfonyloxy-1,8-naphthalimide, N-nonafluoropropane-sulfonyloxy-1,8-naphthalimide, N-nonafluoroethane-sulfonyloxy-1,8-naphthalimide, N-nonafluoromethane-sulfonyloxy-1,8-naphthalimide, triphenylsulfonium perfluorooctanesulfonate, triphenylsulfonium perfluorobutanesulfonate, triphenylsulfonium trifluoromethanesulfonate, triphenylsulfonium hexafluorophosphate, triphenylsulfonium hexafluoroantimonate, diphenyliodonium perfluorooctanesulfonate, diphenyliodonium perfluorobutanesulfonate, diphenyliodonium trifluoromethanesulfonate, diphenyliodonium hexafluorophosphate, diphenyliodonium hexafluoroantimonate, n-hydroxynaphthalimide perfluorobutanesulfonate, and n-hydroxynaphthalimide trifluoromethanesulfonate.

9. The method of claim 2, wherein the partition walls are removed utilizing a lift-off method which removes the partition walls by using a fluorine-based solvent.

10. The method of claim 9, wherein the fluorine-based solvent comprises at least one hydrofluoroether (HFE) selected from the group consisting of methyl nonafluorobutyl ether, methyl nonafluoroisobutyl ether, an isomeric mixture of methyl nonafluorobutyl ether and methyl nonafluoroisobutyl ether, ethyl nonafluorobutyl ether, ethyl nonafluoroisobutyl ether, an isomeric mixture of ethyl nonafluorobutyl ether and ethyl nonafluoroisobutyl ether, 3-ethoxy-1,1,1,2,3,4,4,5,5,6,6,6-dodecafluoro-2-trifluoromethyl-hexane, and 1,1,1,2,2,3,4,5,5,5-decafluoro-3-methoxy-4-trifluoromethyl-pentane.

11-20. (canceled)

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摘要(译)

一种形成有机材料图案膜的方法，所述方法包括：在第一层的第一区域上形成隔离壁，所述隔离壁包括含间苯二酚芳烃的光敏化合物，所述间苯二酚芳烃包括全氟化碳基团；在所述第一层的第二区域上形成包括有机材料的第二层，所述第二区域由所述分隔壁限定；去除隔墙。

